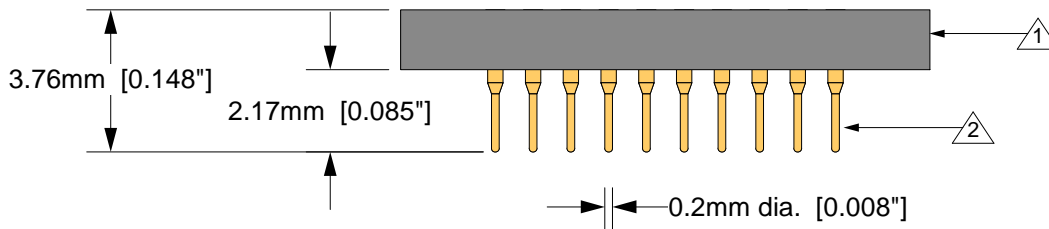


Top View




Side View

- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. non clad
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket
 100 position BGA surface mount land pattern to terminal pins (1.0mm centers, 16x11 array)



Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

LS-BGA100L-41 Drawing		Status: Released	Scale: 8:1	Rev: A
 <p>© 2017 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: M. Tully		Date: 4/12/17	
	File: LS-BGA100L-41 Dwg.mcd		Modified:	